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[Identification of Document] Abstract

[Abstract]

[Object]

In an electrostatic chuck, to reduce particles generated by robbing projection portions and a wafer and to improve a temperature uniformity of the wafer.

[Solving Means]

An electrostatic chuck 1 having an insulation layer 2 includes a mount plane 2a on which a wafer 10 is mounted, an inner electrode provide in the insulation layer 2, and projecting portions 3A protruded from the mount plane 2a which include contact planes 14 to be contacted to the wafer 10. A backside gas is flowed into a space 11 defined by the mount plane 2a, the projecting portions 3A, and the wafer 10 under such a condition that the wafer 10 is attracted to the mount plane so as to maintain a temperature uniformity of the wafer 10. A total amount of areas of the contact planes 14 of the projecting portions 3A contacting to the wafer 10 is not less than 5% and not more than 10% with respect to an area of the inner electrode, and heights H of the projecting portions 3A are not less than 5 μm and not more than 10 μm .

[Selected Figure] Fig. 2